

Product/Process Change Notice (PCN)



- Major change
 Minor change

PCN #: PCN_FeCBF_20160322_Capacity_Increase

Product Affected: WE-CBF

PCN Date: 01.05.2016

Effective Date: 01.08.2016

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- Product Mark
 Date Code
 Packaging
 Others

Attachment: Yes No

Samples:

DESCRIPTION AND PURPOSE OF CHANGE:

In order to increase the production capability Würth Elektronik eiSos GmbH & Co. KG will implement another production line.

There will be no change in form, fit, function, quality or reliability of the product.

DETAIL OF CHANGE:

The production lines can be identified by the first three digits of the lot number.

1. Lot No. of already established production line:

Lot number starting with 187

Country of Origin: Taiwan

Lot No. of additional production line:

Lot number starting with 241

Country of Origin: Taiwan

2. Affected part numbers:

Size	Part number
WE-CBF	742792311
1210	742792312

RELIABILITY / QUALIFICATION SUMMARY:

Process approval is according to internal requirements released by the Quality Department and the Product Management Department.

Please see the Reliability Overview as below. All Tests were passed

	Test	Qty	Reference	Test conditions
1	High Temperature Exposure (Storage)	0/30	MIL-STD-202 Method 108	Preconditioning : 1 time lead-free Heat exposure Temperature: 125±3°C* Testing time: 500h Unpowered. Measurement at 24±2 hours after test conclusion.
2	Moisture Resistance	0/30	MIL-STD-202 Method 106	Preconditioning : 1 time lead-free Heat exposure Time/Cycle = 24 h; Temperature: 65±2°C 500h, Humidity: 95%, Unpowered. Measurement at 24±2 hours after test conclusion.
3	Operational Life	0/30	MIL-PRF-27	Preconditioning : 1 time lead-free Heat exposure Testing time: 1000h Temperature: Ambient Temp. 85±5°C* + rated current = 125°C* Measurement at 24±2 hours after test conclusion.
4	Terminal Strength (SMD)	0/30	internal spec.	Preconditioning : Solder components on test board (lead-free) Apply an individual force for 60 seconds. Please refer the attached table in the description below.
5	Vibration	0/30	MIL-STD-202 Method 204	Preconditioning : Solder components on test board (lead-free) 10g's for 20 minutes, 12 cycles each of 3 orientations. Note: Use 8"X5" PCB, .031" thick, 7 secure points on one long side and 2 secure points at corners of opposite sides. Parts mounted within 2" from any secure point. Test from 15-2000 Hz.
6	Five Time Reflow	0/30	J-STD-020D	Lead -free soldering profile: Peak temperature according to table 4.2 of the J-STD-020
7	Solderability	0/30	JESD22-B102	For both Leaded & SMD. Electrical Test not required. Magnification 50X. Conditions: SMD: a) Method B, Steam Aging 4 hrs @ 98% r.H.@ 245°C
8	Thermal Shock	0/30	MIL-STD-202 Method 107	Preconditioning : 1 time lead-free Heat exposure Temperature: -40°C/+125°C* Dwell time is 30 minutes. Cycles: 300 Transfer time max. 20s.
9	Board Flex	0/30	AEC-Q200-005	Preconditioning : Solder components on test board (lead-free) Appendix 2 Note: 2mm (Min) Sample size: 30
10	Low Temperature Storage Life	0/30	JESD22-A119	Preconditioning : 1 time lead-free Heat exposure Temperature: -55±3°C Testing time: 500h Measurement at 24±2 hours after test conclusion.

Note: *Use max. or min. temperatures according Würth Elektronik data sheet (current version) 30 pcs of each DUT (Device Under Test)

DATA SHEET CHANGE:

Yes

No

Würth Elektronik eiSos GmbH & Co. KG

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